Dynamic Engineers Inc.

2550 Gray Falls Dr., Suite#128, Houston, TX, 77077 USA TEL: 1-281-870-8822 EMAIL:Sales@DynamicEng.com

H7 L C &) &\$5 C ! &* A < n! B ! J CH Á ÁCHEÁ ÁEI Á { ÁUT ÖÁ ÔÝUÁ

Features and Benefits

26MHz clipped sine wave output
2.5 mm x 2.0 mm x 0.8mm SMD package
±0.5 ppm frequency stability (over -30°C to +85°C)
3.3V supply voltage
1.3mA low power consumption

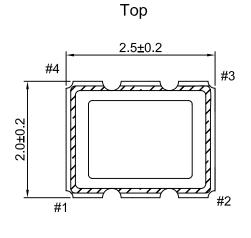
Typical Applications

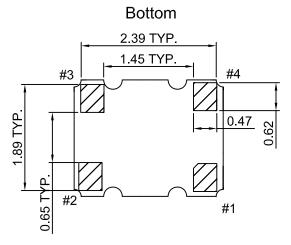
WIFI/WIMAX, WLAN GPS Mobile phone

Mechanical Drawing & Pin Connections

Drawing No:

MD1*00'(!&





Side Wax.

Unit in mm

1mm = 0.0394 inches

Pin Connection

Name	Connection			
Pin 1	Control Voltage			
Pin 2	GND			
Pin 3	OUTPUT			
Pin 4	Supply Voltage			

Dynamic Engineers Inc.

H7 L C &) &\$5 C ! &* A < n-B ! J CH Á ÁCHEÁ ÁE Á { ÁUT ÖÁ ÓÝ U Á

2550 Gray Falls Dr., Suite#128, Houston, TX, 77077 USA TEL: 1-281-870-8822 EMAIL:Sales@DynamicEng.com

Specifications

Oscillator	Come	Condition	Value			Heit	Mata
Specification	Sym		Min.	Тур.	Max.	Unit	Note
Nominal Frequency	Fo			26		MHz	
Output Waveform			Clipp	Clipped Sine Wave			
Output Level			0.8		1.2	Vp-p	
Output Load			10Kohm//10pF				
Start Time		90% of final RF level in Vp-p			2	msec	
Harmonics					-5.0	dBc	
Power Supply							
Supply Voltage	V_{DD}	±5%		3.3		V	
Supply Current					1.3	mA	
Control Voltage							
Control Voltage			0.4	1.4	2.4	V	
Pulling Range			±9		±15	ppm/V	
Frequency Stability							
Frequency Tolerance		Frequency at 25°C ±3°C, Vcon=1.4V			±1.5	ppm	
Frequency Stability Vs. Temperature		From -30°C to +85°C Referenced to the midpoint between minimum and maximum frequency value			±0.5	ppm	
Static Temperature Hysteresis					±0.6	ppm	
Supply Voltage Change		Supply voltage varied ±5%			±0.2	ppm	
Load Sensitivity		±10% load change			±0.2	ppm	
Aging		at +25°C 1 st year		1	±1	ppm	
Phase Noise		@ 1KHz			-130	dBc / Hz	
Environmental Conditions		Reference Standards	Test Co	ndition			
Operating Temperature Range			-30°C to	-30°C to +85°C			
Storage Temperature Range			-40°C to	+85°C			
Note		•					

- 1. Touch the solder iron at 260°C +/-5°C onto the leads for 10 +/-2 sec max or touch the solder at 350°C +/-5°C onto the leads for 3+/-0.5 sec.
- 2. In the customer's reflow process, if it will remain some mechanical stress at the soldering terminals, also make some cracks on the soldering termination. Some cracks will cause open or short circuit and cause of thermal increasing or smoking. Don't make any excess mechanical stress to soldering points.
- 3. In case of giving a heavy shock to the products, it may make an open or short circuit and cause of thermal increasing and smoking. To avoid heavy shock impact applying to products is strictly required.

RECOMMENDED IR REFLOW PROFILE

